Please replace the fourth full paragraph on page 27 with the following:

While a variety of methods may be used to fabricate stabilizers 50, the use of a stereolithographic process as exemplified above is a preferred method because a large number of stabilizers 50 may be fabricated in a short time, the stabilizer height and position are computer-controlled to be extremely precise, wastage of unconsolidated material 86 is minimal, and the stereolithography method requires less handling of semiconductor devices 10, test substrates 20, or other substrates than the other viable methods indicated above.

Please replace the abstract on page 41 with the following:

ABSTRACT OF THE DISCLOSURE

Stabilizers to be disposed on a surface of a semiconductor device or test substrate and methods of fabricating and disposing the stabilizers on semiconductor devices and test substrates. Semiconductor devices and test substrates including the stabilizers are also disclosed, as well as assemblies wherein the stabilizers are disposed between a semiconductor device and a test substrate. One or more of the stabilizers are disposed on the surface of a semiconductor device or test substrate prior to bonding the semiconductor device face-down upon the test substrate. Upon assembly of the semiconductor device face-down upon a test substrate and establishing electrical communication between contact pads of the semiconductor device and test pads of the test substrate, such as with conductive structures, the stabilizers prevent the semiconductor device from tipping or tilting relative to the test substrate. The stabilizers may be preformed structures which are attached to a surface of a semiconductor device, test substrate, or both. Alternatively, the stabilizers can be fabricated on the surface of the semiconductor device, the test substrate, or both. A stereolithographic method of fabricating the stabilizers is disclosed. The stereolithographic method may include use of a machine vision system including at least one camera operably associated with a computer controlling a stereolithographic application of material so that the system may recognize the position and orientation of a semiconductor device or test substrate on which the stabilizer is to be fabricated.